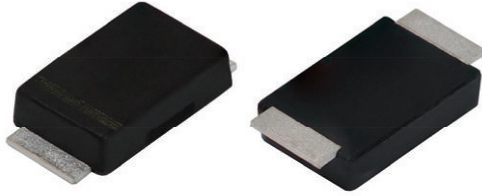




**THE DATASHEET OF  
VSS8D3M10HM3/H**



# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier

**eSMP<sup>®</sup> Series**


Top View

Bottom View

**SlimSMAW (DO-221AD)**

Cathode Anode

**LINKSTO ADDITIONAL RESSOURCES**


PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	3 A
$V_{RRM}$	100 V
$I_{FSM}$	60 A
$V_F$ at $I_F = 3$ A (125 °C)	0.58 V
$T_J$ max.	175 °C
Package	SlimSMAW (DO-221AD)
Circuit configuration	Single

**FEATURES**

- Low-profile package
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Compatible to SOD-128 package case outline
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**
**TYPICAL APPLICATIONS**

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

**MECHANICAL DATA**
**Case:** SlimSMAW (DO-221AD)

Molding compound meets UL 94 V-0 flammability rating  
 Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

H3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** color band denotes cathode end

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	VSS8D3M10	UNIT
Device marking code		3M10	
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	V
Maximum average forward rectified current (fig.1)	$I_F^{(1)}$	3	A
	$I_F^{(2)}$	2.1	
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	$I_{FSM}$	60	A
Operating junction temperature range	$T_J^{(3)}$	-40 to +175	°C
Storage temperature range	$T_{STG}$	-55 to +175	

**Notes**

- (1) Mounted on 30 mm x 30 mm AL PCB pad area
- (2) Free air, mounted on recommended copper pad area
- (3) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 1.5\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.55	-	V
	$I_F = 3\text{ A}$			0.67	0.75	
	$I_F = 1.5\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.48	-	
	$I_F = 3\text{ A}$			0.58	0.66	
Reverse current	$V_R = 70\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.003	-	mA
		$T_A = 125\text{ }^\circ\text{C}$		0.7	-	
	$V_R = 100\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		-	0.2	
		$T_A = 125\text{ }^\circ\text{C}$		1.5	4	
Typical junction capacitance	4.0 V, 1 MHz		$C_J$	340	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
(2) Pulse test: pulse width  $\leq 5\text{ ms}$

THERMAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise specified)				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	120	150	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	12	15	

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$   
(2) Thermal resistance junction-to-ambient to follow JEDEC<sup>®</sup> 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint  
(3) Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
VSS8D3M10-M3/H	0.033	H	3500	7" diameter plastic tape and reel
VSS8D3M10-M3/I	0.033	I	14 000	13" diameter plastic tape and reel
VSS8D3M10HM3/H <sup>(1)</sup>	0.033	H	3500	7" diameter plastic tape and reel
VSS8D3M10HM3/I <sup>(1)</sup>	0.033	I	14 000	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

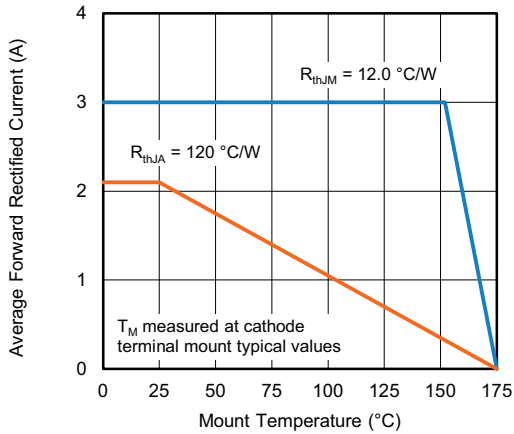


Fig. 1 - Maximum Forward Current Derating Curve

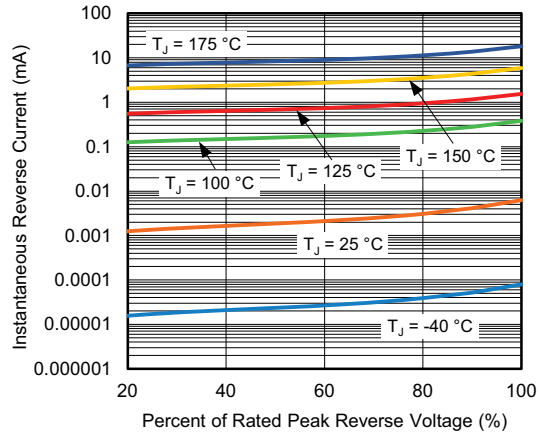


Fig. 4 - Typical Reverse Leakage Characteristics

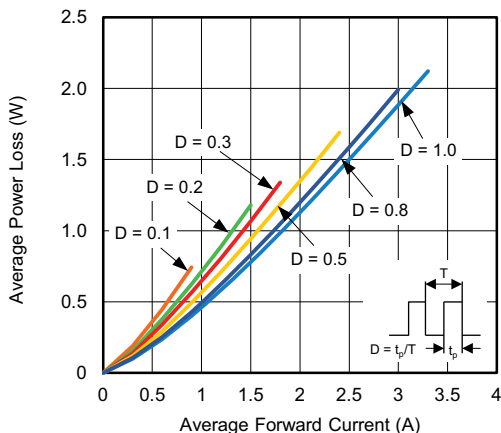


Fig. 2 - Forward Power Loss Characteristics

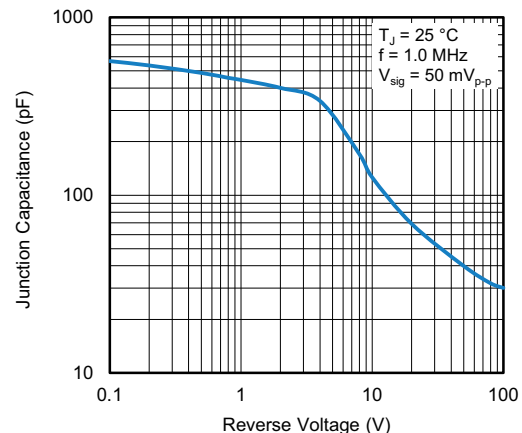


Fig. 5 - Typical Junction Capacitance

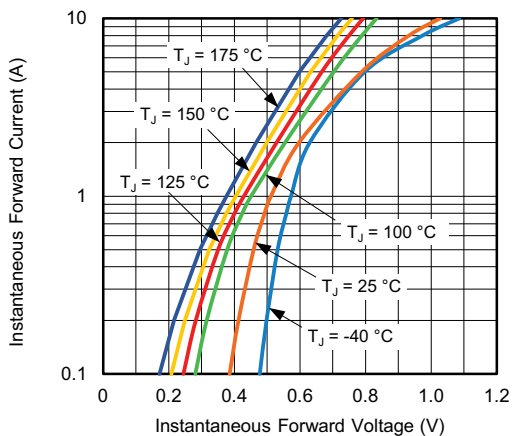


Fig. 3 - Typical Instantaneous Forward Characteristics

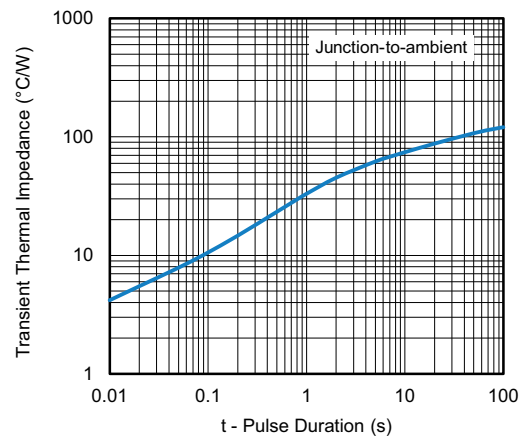
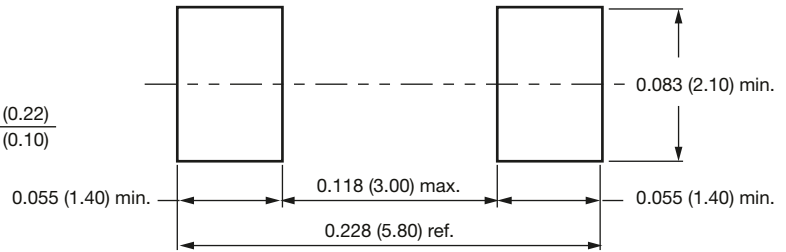
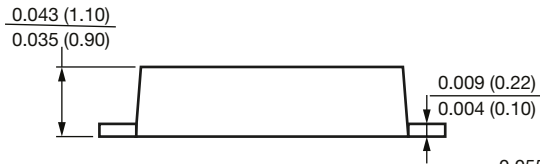
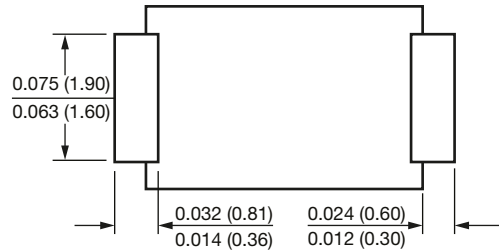
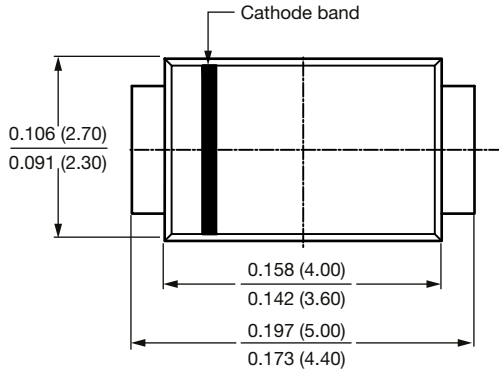


Fig. 6 - Typical Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SlimSMAW (DO-221AD)



Mounting pad layout



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